



NOEL Technologies

RESIST SPIN COATING THICKNESS RANGES

Resist Type	Nominal Thickness	Full Thickness Range from Manufacturer Curves	H/P Hard Bake	Notes
TARF P6111	1600A	1600A-2000A	3.0 Minutes @ 125°C	DUV 193nm
660-6	6,000A	5,880A - 11,000A	3.0 Minutes @125°C	I-Line 365
TARF P7052	6,000A	3,450A - 7,140A	3.0 Minutes @125°C	DUV 193nm
UV 210-3	7,200A	7,056A - 7,344A	3.0 Minutes @125°C	DUV 248nm
1811	10,000A	9,800A - 10,200A	3.0 Minutes @125°C	I-Line 365
UV 6-1.2	2.0µm	19,600A - 20,400A	5.0 Minute @115°C	DUV 248nm
3012	2.0µm	19,600A - 20,400A	5.0 Minutes @125°C	I-Line 365
UV 6-1.2	2.5µm	24,500A -25,500A	5.0 Minute @ 25°C	DUV 248nm
3012	2.5µm	24,500A -25,500A	5.0 Minutes @125°C	I-Line 365
3012	3.0µm	29,400A - 30,600A	5.0 Minutes @125°C	I-Line 365
220-3	3.5µm	34,300A - 35,700A	5.0 Minutes @125°C	I-Line 365
9272M - 6.0	4.8µm	47,040A - 48,960A		
220-3	5.0µm	49,000A - 51,000A	5.0 Minutes @125°C	I-Line 365
220-3	7.0µm	68,600A - 71,400A	5.0 Minutes @125°C	I-Line 365
220-7	10.0µm	97,000A - 103,000A	5.0 Minutes @125°C	I-Line 365
SIPR 7500W T50*	30.0µm	294,000A - 306,000A	15 minutes @125°C	I-Line 365

* Denotes a thick plating results manufactured by Shin Etsu.

Noel validates the thickness via optical metrology to validate mean thickness range on silicon substrates on resists <10.0um, resist > 10.0um a step height measurement is taken on silicon substrates.

Thickness tolerance ±2%